R8C/M12A Group

Power Control in Wait Mode

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Abstract

This document describes the setting method and an application example for power control using wait mode in the R8C/M12A Group.

Product

MCU: R8C/M12A Group

When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

Contents

1. Specifications

After reset and setting the operating mode, the MCU enters wait mode. The MCU returns from wait mode by the falling edge input of the $\overline{\text{INT0}}$ pin or a timer interrupt every second. This document describes the two sample programs described below.

- Sample program 1
  Reset → Low-speed on-chip oscillator mode (no division) → High-speed on-chip oscillator mode (no division) → Wait mode → High-speed on-chip oscillator mode (no division)
- Sample program 2
  Reset → Low-speed on-chip oscillator mode (no division) → Low-speed on-chip oscillator mode (divided-by-8) → Wait mode → Low-speed on-chip oscillator mode (no division) → High-speed clock mode (no division)

Tables 1.1 and 1.2 list the Peripheral Functions and Their Applications (Sample Programs 1 and 2). Figures 1.1 to 1.2 show Usage Examples.

Table 1.1 Peripheral Functions and Their Applications (Sample Program 1)

Peripheral Function	Application
$\overline{\text{INT0}}$ interrupt	Return from wait mode
Timer RJ2	Count source of timer RB2
Timer RB2	Return from wait mode

Table 1.2 Peripheral Function and Its Application (Sample Program 2)

Peripheral Function	Application
Timer RJ2	Return from wait mode

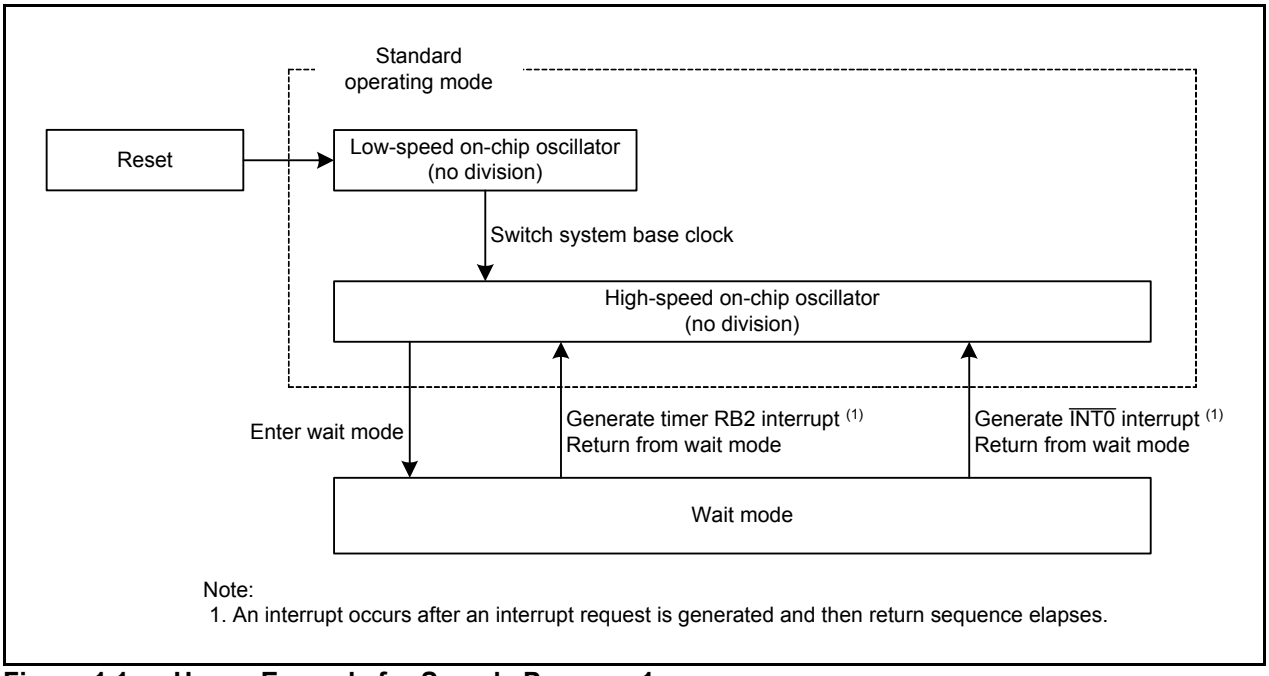


Figure 1.1 Usage Example for Sample Program 1

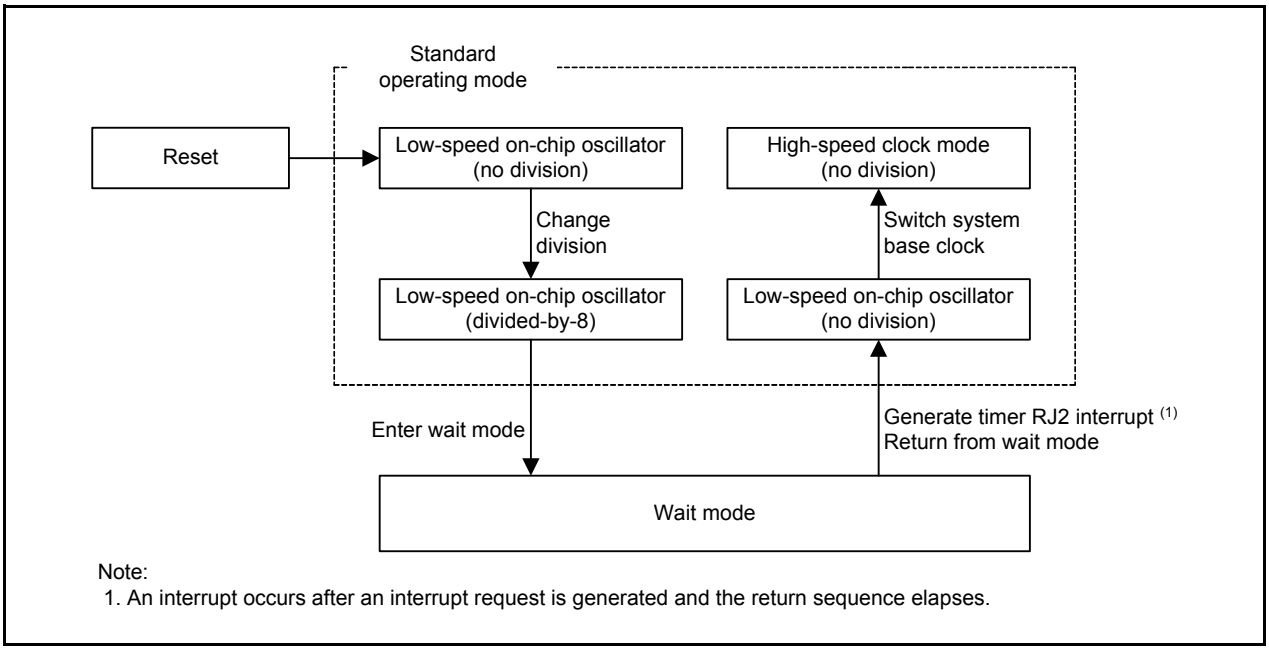


Figure 1.2 Usage Example for Sample Program 2

2. Operation Confirmation Conditions

The sample code accompanying this application note has been run and confirmed under the conditions below.

Table 2.1 Operation Confirmation Conditions

Item	Contents
MCU used	R8C/M12A Group
Operating frequencies	Sample program 1 • High-speed on-chip oscillator clock: 20 MHz (typical) • System clock (f) (before entering wait mode): 20 MHz (typical) • System clock (f) (after returning from wait mode): 20 MHz (typical) • CPU clock (fs) (before entering wait mode): 20 MHz (typical) • CPU clock (fs) (after returning from wait mode): 20 MHz (typical) Sample program 2 • Low-speed on-chip oscillator clock: 125 kHz (typical) • XIN clock: 20 MHz • System clock (f) (before entering wait mode): 125 kHz (typical) • System clock (f) (after returning from wait mode): 125 kHz (typical) • System clock (f) (after switching system base clock): 20 MHz • CPU clock (fs) (before entering wait mode): 15.625 kHz (typical) • CPU clock (fs) (after returning from wait mode): 125 kHz (typical) • CPU clock (fs) (after switching system base clock): 20 MHz
Operating voltage	5.0 V (2.7 to 5.5 V)
Integrated development environment	Renesas Electronics Corporation High-performance Embedded Workshop Version 4.07
C compiler	Renesas Electronics Corporation M16C Series, R8C Family C Compiler V.5.45 Release 01
	Compile options -D__UART0__ -c -finfo -dir "$(CONFIGDIR)" -R8C (Default setting is used in the integrated development environment.)

3. Hardware

3.1 Pin Used

Table 3.1 lists the Pin Used and Its Function.

Table 3.1 Pin Used and Its Function

Pin Name	I/O	Function
P1_4/$\overline{\text{INT0}}$	Input	$\overline{\text{INT0}}$ interrupt input

4. Software for Sample Program 1

4.1 Operation Overview of Sample Program 1

After reset, the MCU enters high-speed on-chip oscillator mode (no division) from low-speed on-chip oscillator mode (no division) by a program. Disable maskable interrupts, enable the INT0 interrupt input used to return from wait mode, start timer RB2 and timer RJ2 counts, disable CPU rewrite mode, disable the voltage detection circuit, and set a clock after returning from wait mode. Then, enable maskable interrupts and execute the WAIT instruction to enter wait mode.

The system clock stops in wait mode. However, since fHOCO is selected as the count source of timer RJ2, timer RB2 and timer RJ2 continue the count operation. The MCU returns from wait mode using an interrupt by the falling edge input of the INT0 pin or the timer RB2 interrupt every second. A clock immediately before entering wait mode is automatically selected for the CPU clock when returning from wait mode. When the MCU returns from wait mode using the timer RB2 interrupt, it enters wait mode by the WAIT instruction again. When the MCU returns from wait mode using the INT0 interrupt, disable the INT0 interrupt input, and stop timer RB2 and timer RJ2.

(1) Oscillate the high-speed on-chip oscillator by a program after reset.
(2) After waiting until oscillation of the high-speed on-chip oscillator stabilizes, switch the operating mode from low-speed on-chip oscillator mode (no division) to high-speed on-chip oscillator mode (no division) and stop the low-speed on-chip oscillator.
(3) Disable maskable interrupts, and perform the settings described below.

Settings
- Enable the $\overline{\text{INT0}}$ interrupt input.
- Start the timer RB2 and timer RJ2 count.
- Disable CPU rewrite mode.
- Disable voltage detection.
- Set the WCKSTP bit in the CKSTPR register to 1 (the system clock stops in wait mode).
- Set the PHISRS bit in the CKRSCR register to 0 (setting values of bits PHISSEL0 to PHISSEL2 in the SCKCR register are enabled).
- Set the WAITRS bit in the CKRSCR register to 0 (return from wait mode using the system base clock immediately before entering wait mode).
- Set 1 to the variable (mode).

(4) Enable maskable interrupts, and execute the WAIT instruction to enter wait mode.
(5) Return from wait mode using the timer RB2 interrupt (every second) or $\overline{\text{INT0}}$ interrupt (falling edge signal). Clocks set in (3) are selected for the CPU clock when returning from wait mode.

When the MCU returns from wait mode using the timer RB2 interrupt:
After returning to main processing, the MCU enters wait mode again.

When the MCU returns from wait mode using the $\overline{\text{INT0}}$ interrupt:
Set 0 to the variable (mode) to return to main processing, disable the $\overline{\text{INT0}}$ interrupt input, and stop timer RB2 and timer RJ2.
(6) Repeat steps (3) to (5).

Figure 4.1 shows the Operating Example in Wait Mode.

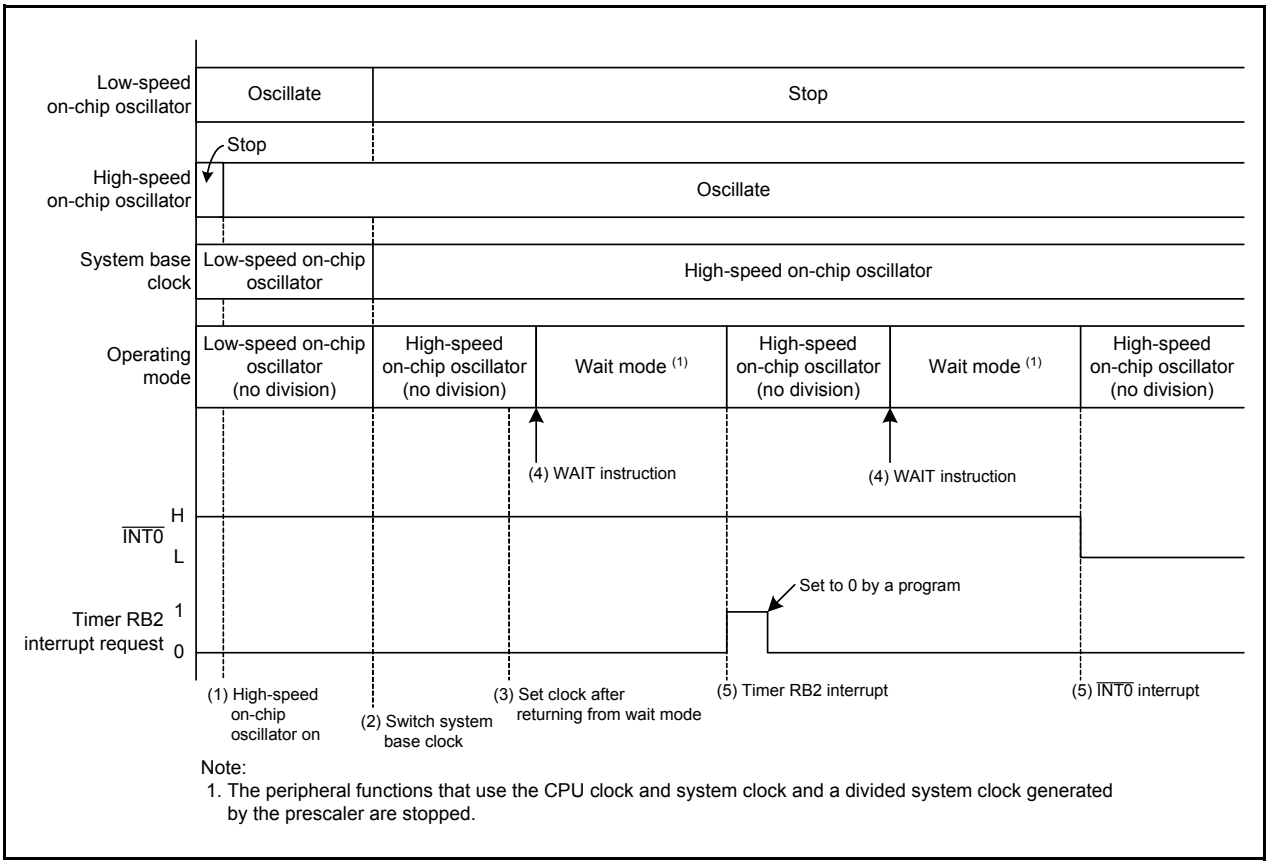


Figure 4.1 Operating Example in Wait Mode

4.2 Required Memory Size

Table 4.1 lists the Required Memory Size.

Table 4.1 Required Memory Size for Sample Program 1

Memory Used	Size	Remarks
ROM	443 bytes	In the r01an0370_src_sample1.c module
RAM	1 byte	In the r01an0370_src_sample1.c module
Maximum user stack usage	10 bytes	
Maximum interrupt stack usage	18 bytes	

The required memory size varies depending on the C compiler version and compile options.

4.3 Variables

Table 4.2 lists the Global Variable.

Table 4.2 Global Variable

Type	Variable Name	Contents	Function Used
unsigned char	mode	Select to enter wait mode	power_control, _int0

4.4 Functions

Table 4.3 lists the Functions.

Table 4.3 Functions

Function Name	Outline
mcu_init	System clock setting
int0_init	Initial setting of $\overline{\text{INT0}}$ interrupt
timer_rj2_init	Initial setting of timer RJ2
timer_rb2_init	Initial setting of timer RB2
power_control	Wait mode processing
_int0	$\overline{\text{INT0}}$ interrupt handling
_timer_rb	Timer RB2 interrupt handling

4.5 Function Specifications

The following tables list the sample code function specifications.

mcu_init	
Outline	System clock setting
Header	None
Declaration	void mcu_init(void)
Description	Set the system clock.
Argument	None
Returned value	None
Remark	—

int0_init	
Outline	Initial setting of $\overline{\text{INT0}}$ interrupt
Header	None
Declaration	void int0_init(void)
Description	Perform initial setting to use the $\overline{\text{INT0}}$ interrupt.
Argument	None
Returned value	None
Remark	—

timer_rj2_init	
Outline	Initial setting of timer RJ2
Header	None
Declaration	void timer_rj2_init(void)
Description	Perform initial setting to use timer RJ2 in timer mode.
Argument	None
Returned value	None
Remark	—

timer_rb2_init	
Outline	Initial setting of timer RB2
Header	None
Declaration	void timer_rb2_init(void)
Description	• Perform initial setting to use timer RB2 in timer mode. • Use timer RJ2 underflow as the count source.
Argument	None
Returned value	None
Remark	—

power_control	
Outline	Wait mode processing
Header	None
Declaration	void power_control(void)
Description	Enter wait mode.
Argument	None
Returned value	None
Remark	—

_int0	
Outline	$\overline{\text{INT0}}$ interrupt handling
Header	None
Declaration	void _int0(void)
Description	Set 0 to the variable (mode).
Argument	None
Returned value	None
Remark	—

_timer_rb	
Outline	Timer RB2 interrupt handling
Header	None
Declaration	void _timer_rb(void)
Description	Perform timer RB2 interrupt handling.
Argument	None
Returned value	None
Remark	—

4.6 Flowcharts

4.6.1 Main Processing

Figure 4.2 shows the Main Processing.

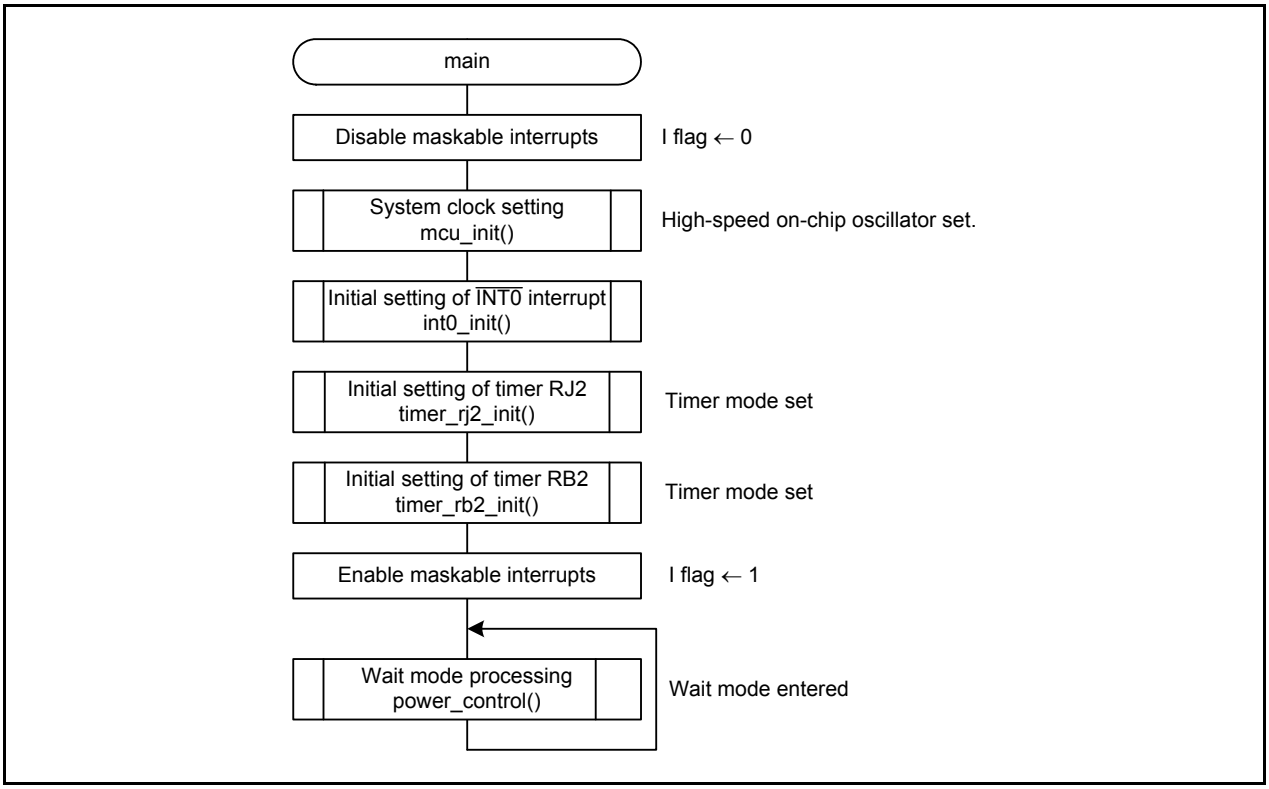


Figure 4.2 Main Processing

4.6.2 System Clock Setting

Figure 4.3 shows the System Clock Setting.

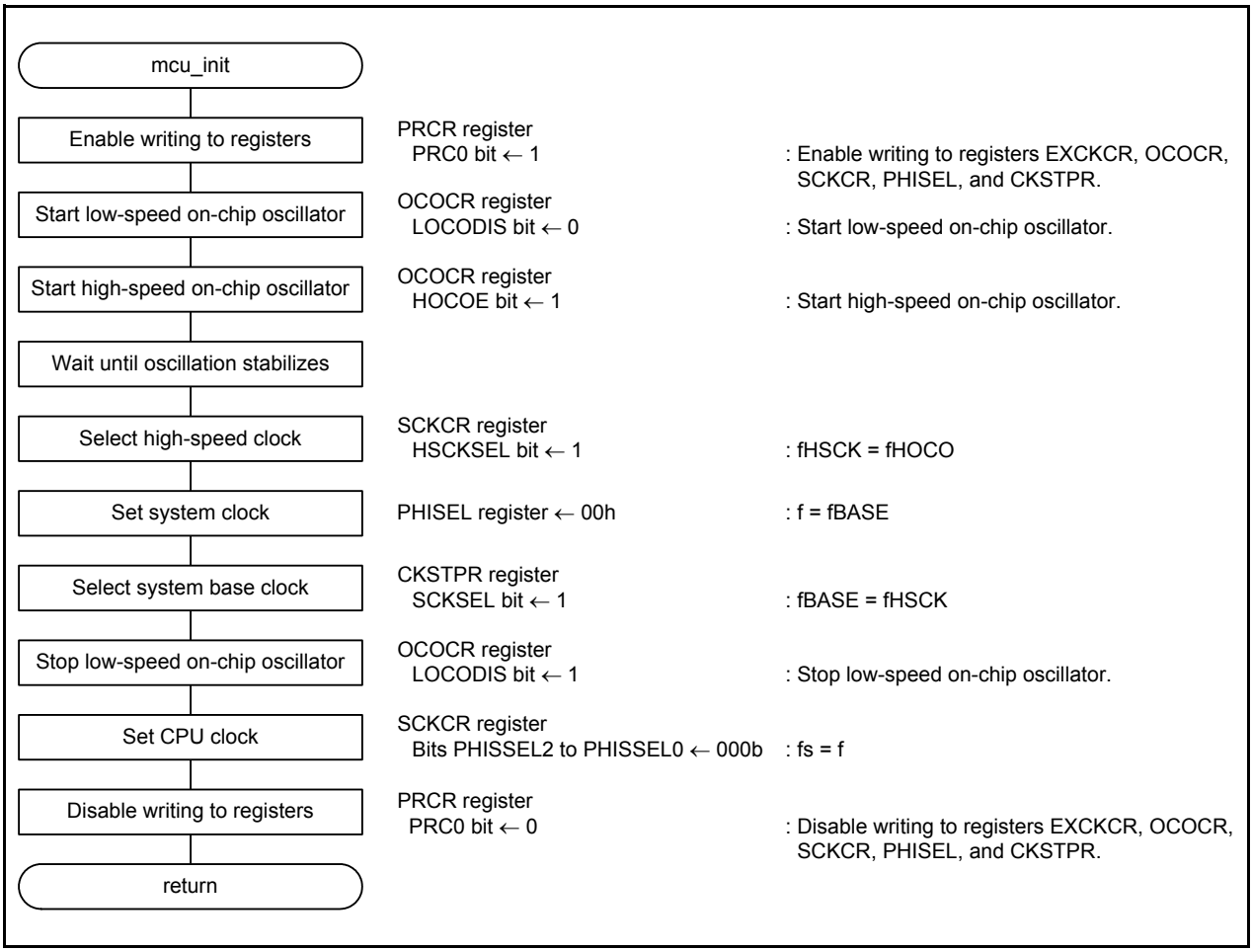


Figure 4.3 System Clock Setting

4.6.3 Initial Setting of the $\overline{\text{INT0}}$ Interrupt

Figure 4.4 shows the $\overline{\text{INT0}}$ Interrupt Setting.

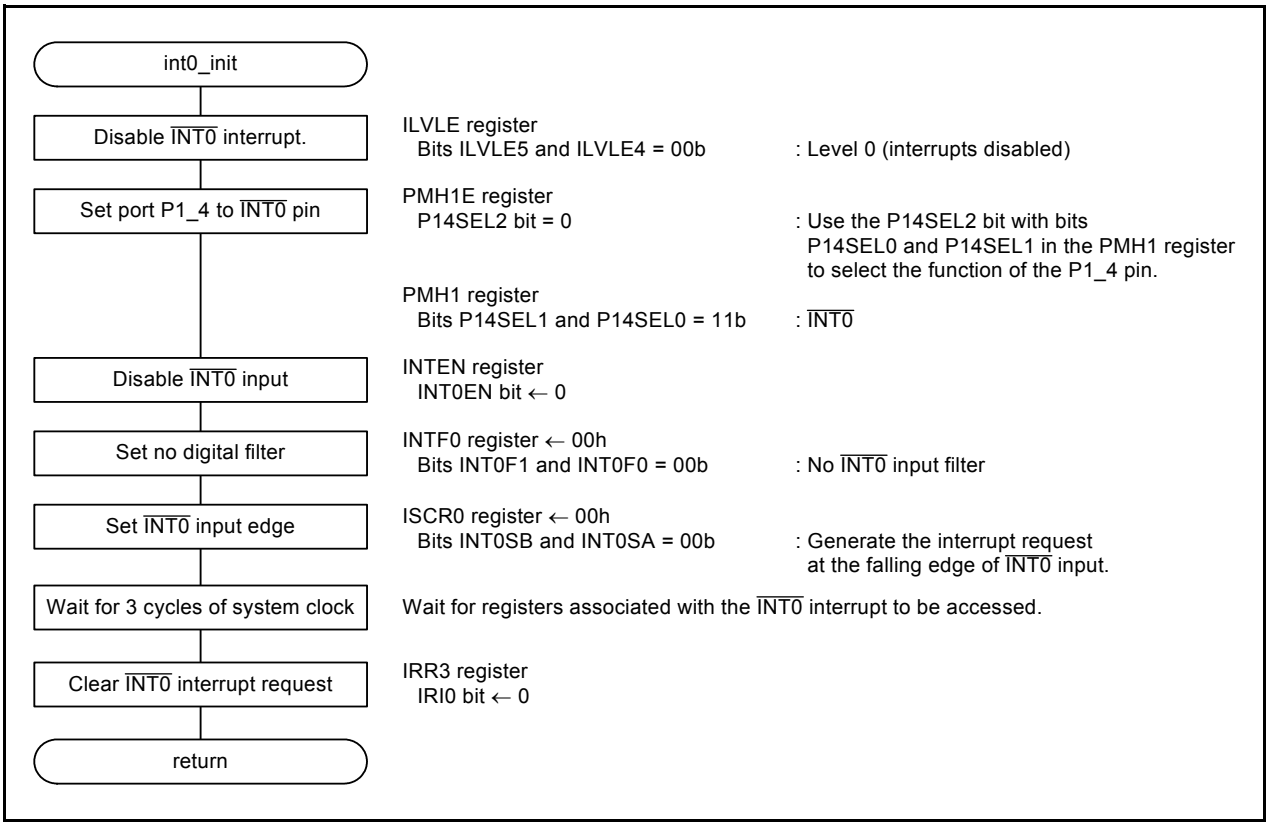


Figure 4.4 $\overline{\text{INT0}}$ Interrupt Setting

4.6.4 Initial Setting of Timer RJ2

Figure 4.5 shows the Initial Setting of Timer RJ2.

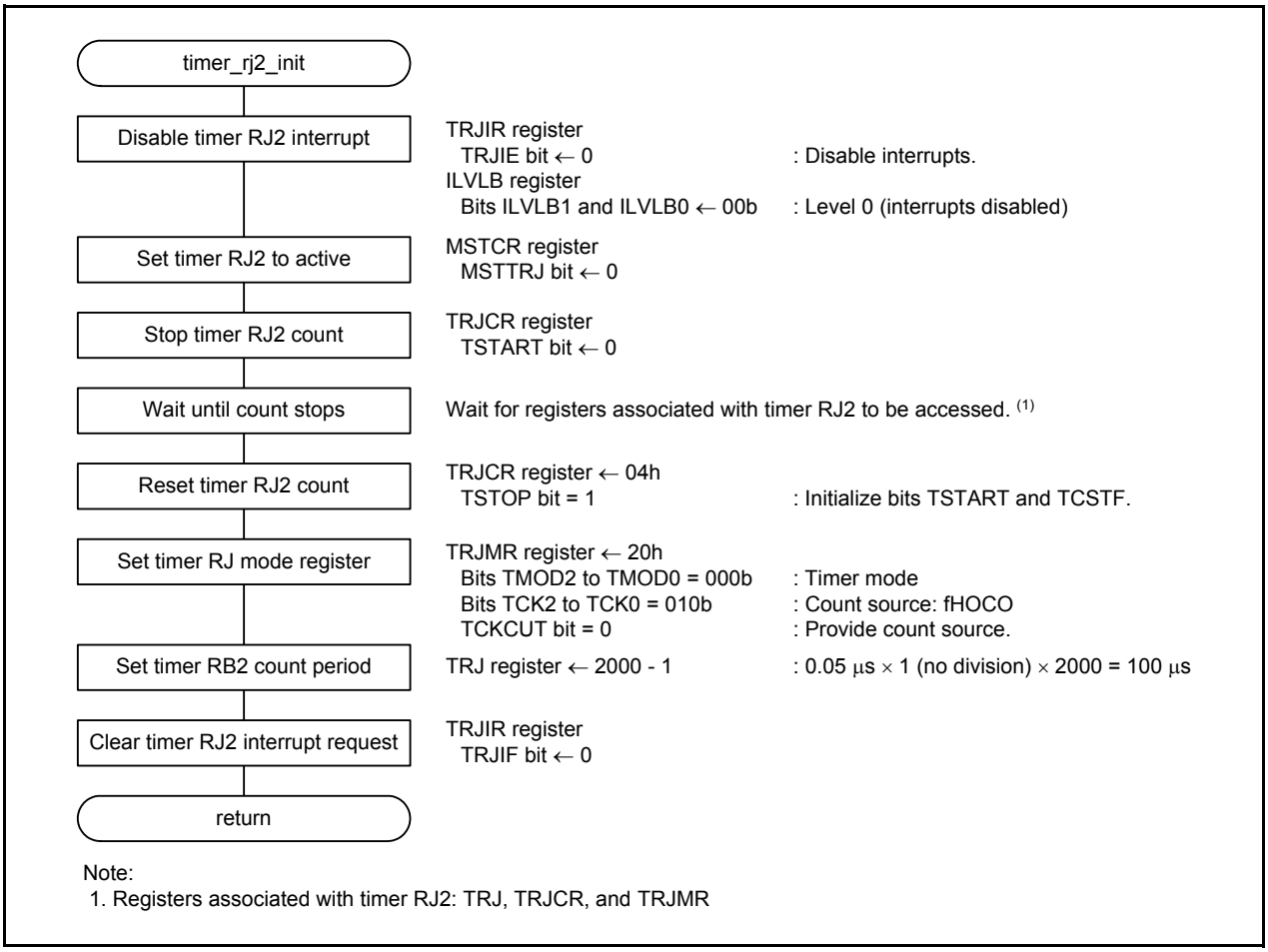


Figure 4.5 Initial Setting of Timer RJ2

4.6.5 Initial Setting of Timer RB2

Figure 4.6 shows the Initial Setting of Timer RB2.

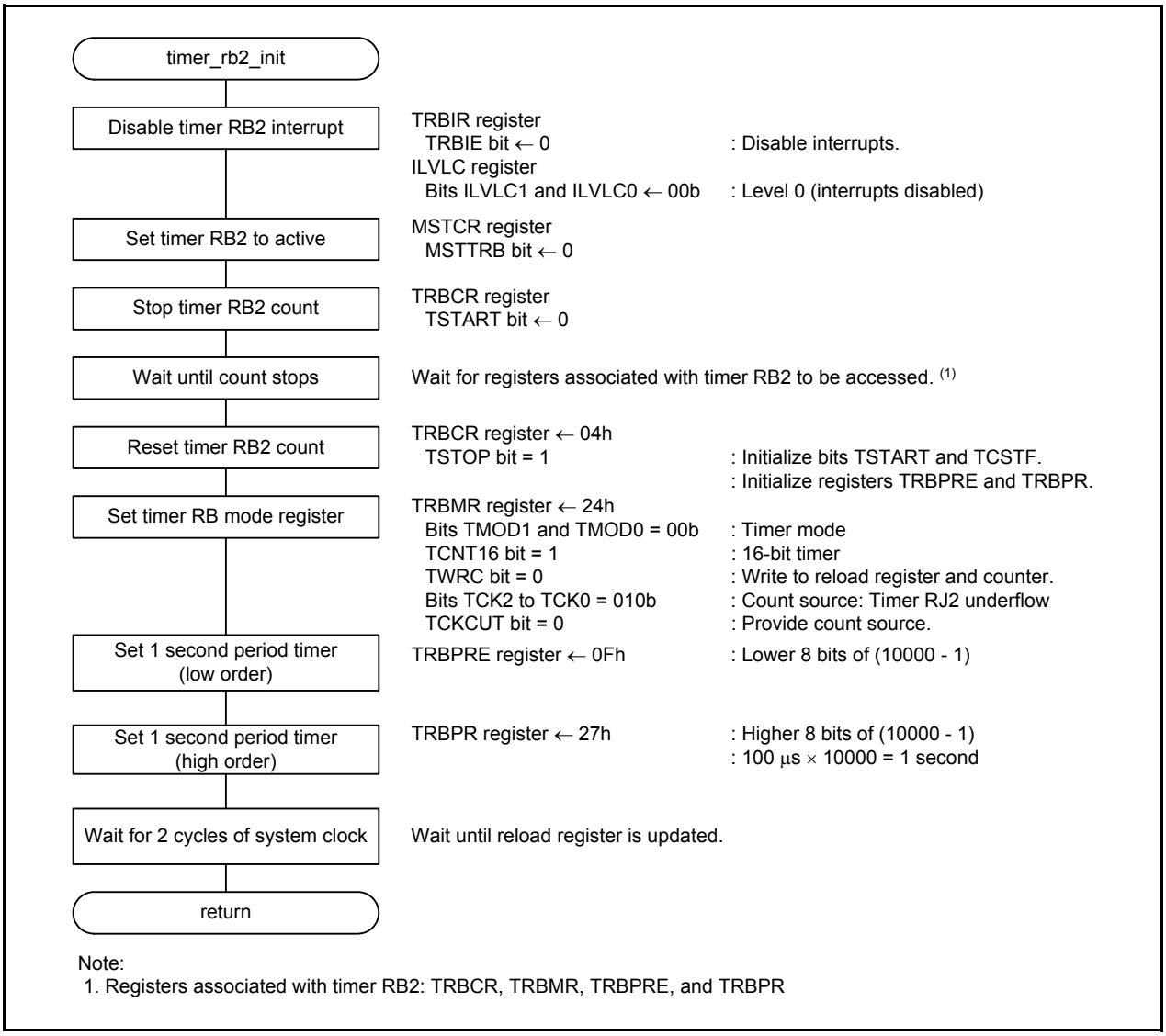
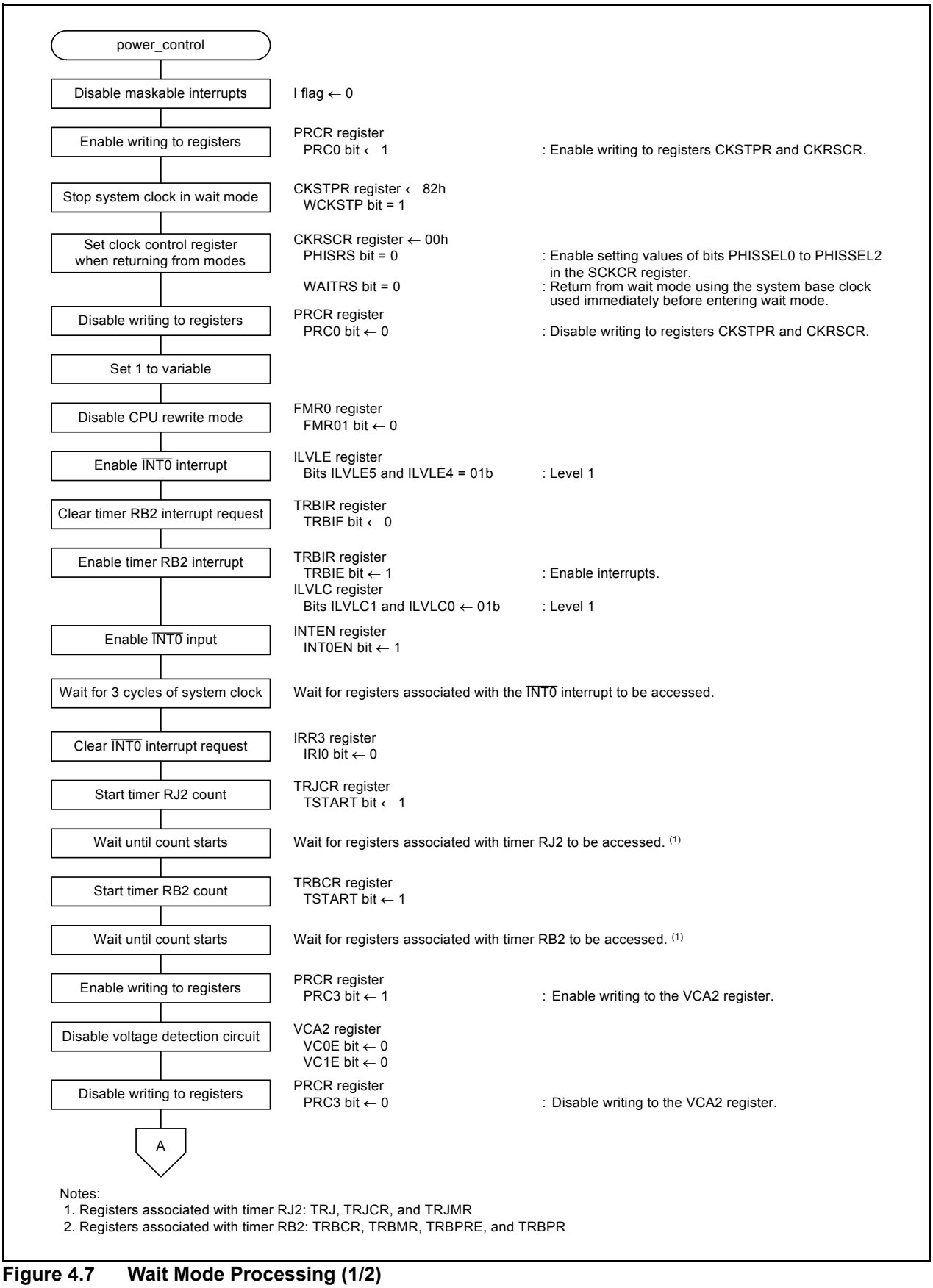


Figure 4.6 Initial Setting of Timer RB2

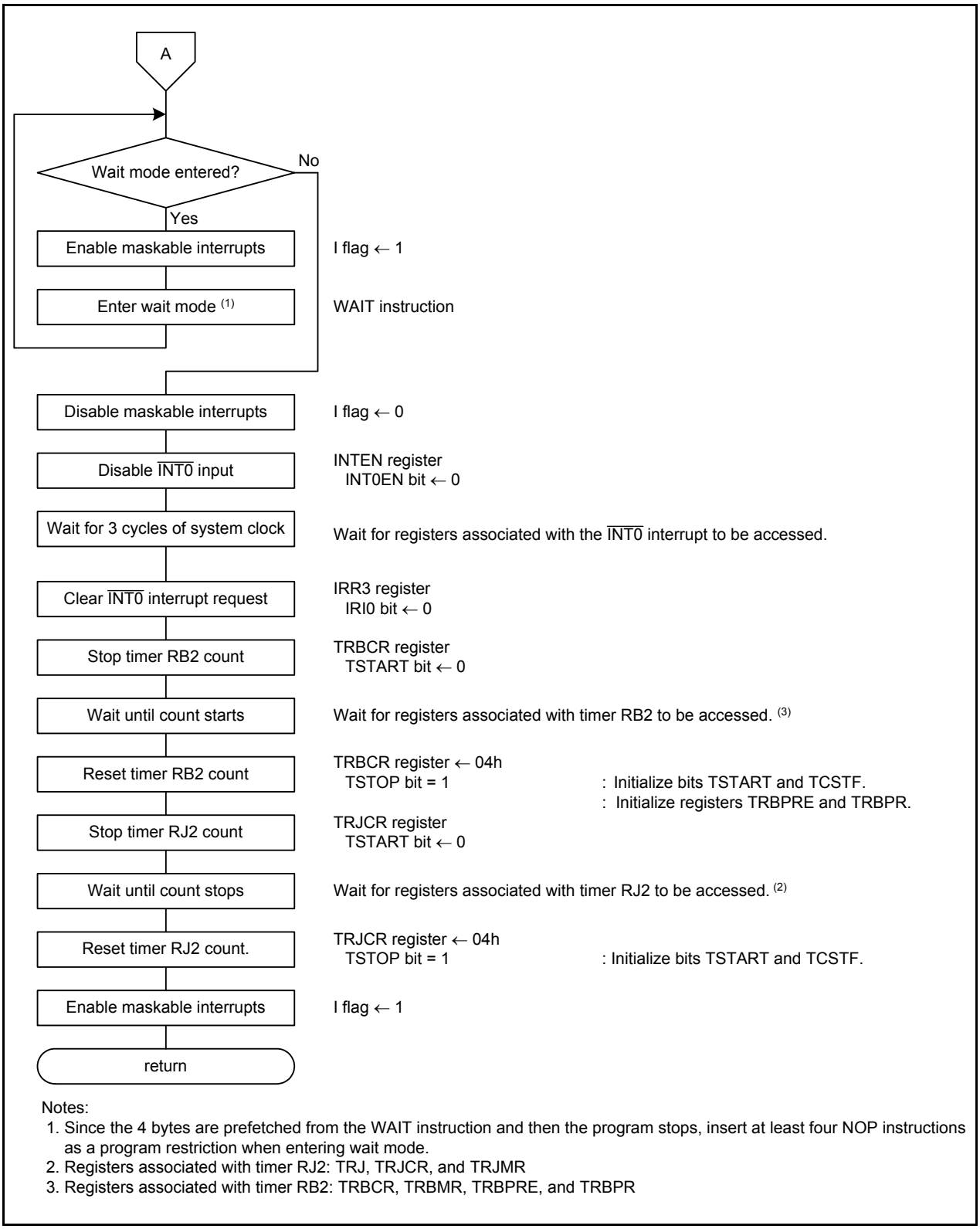
4.6.6 Wait Mode Processing

Figures 4.7 and 4.8 show Wait Mode Processing.



Notes:
1. Registers associated with timer RJ2: TRJ, TRJCR, and TRJMR
2. Registers associated with timer RB2: TRBCR, TRBMR, TRBPRE, and TRBPR

Figure 4.7 Wait Mode Processing (1/2)



Notes:
1. Since the 4 bytes are prefetched from the WAIT instruction and then the program stops, insert at least four NOP instructions as a program restriction when entering wait mode.
2. Registers associated with timer RJ2: TRJ, TRJCR, and TRJMR
3. Registers associated with timer RB2: TRBCR, TRBMR, TRBPRE, and TRBPR

Figure 4.8 Wait Mode Processing (2/2)

4.6.7 $\overline{\text{INT0}}$ Interrupt Handling

Figure 4.9 shows $\overline{\text{INT0}}$ Interrupt Handling.

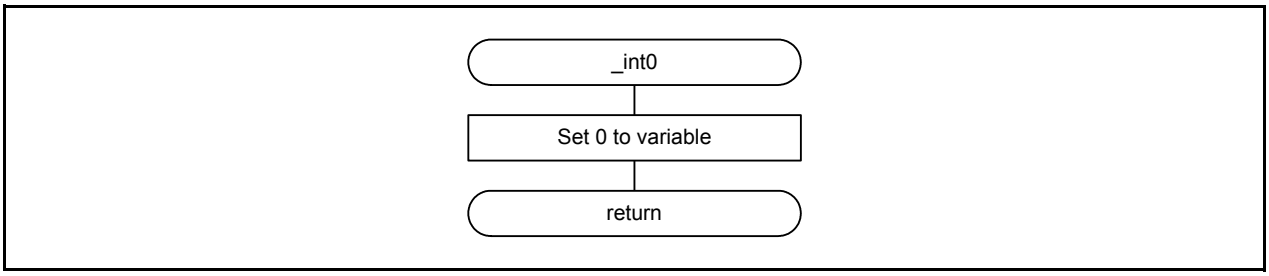


Figure 4.9 $\overline{\text{INT0}}$ Interrupt Handling

4.6.8 Timer RB2 Interrupt Handling

Figure 4.10 shows Timer RB2 Interrupt Handling.

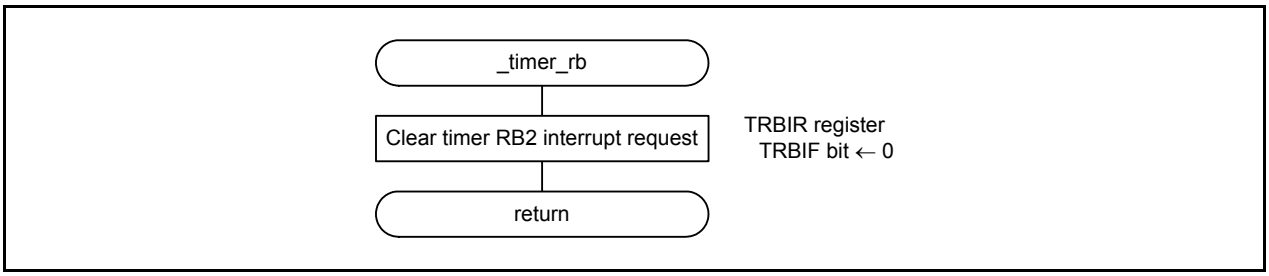


Figure 4.10 Timer RB2 Interrupt Handling

5. Software for Sample Program 2

5.1 Operation Overview of Sample Program 2

After reset, the MCU enters low-speed on-chip oscillator mode (divided-by-8) from low-speed on-chip oscillator mode (no division) by a program. Set the interval of refresh operations in low-current-consumption read mode to the FREFR register, and set the FMR27 bit in the FMR2 register to 1 (low-current-consumption read mode enabled) to use low-current-consumption read mode. Disable maskable interrupts, start the timer RJ2 count used to return from wait mode, disable CPU rewrite mode, disable voltage detection circuit, set a clock after returning from wait mode, disable low-current-consumption read mode, stop flash memory in wait mode, and enable low-power-consumption wait mode. After enabling maskable interrupts, execute the WAIT instruction to enter wait mode.

The MCU returns from wait mode using the timer RJ2 interrupt every second. The low-speed on-chip oscillator mode (no division) is automatically selected for the operating mode when returning from wait mode. Oscillate the XIN clock by a program and enter high-speed clock mode (no division) after waiting until XIN clock oscillation stabilizes.

(1) Set low-speed on-chip oscillator mode (divided-by-8) by a program after reset.
(2) After setting the interval of refresh operations in low-current-consumption read mode, set the FMR27 bit in the FMR2 register to 1 (low-current-consumption read mode enabled).
(3) Disable maskable interrupts, and perform the settings described below.

Settings
- Start the timer RJ2 count.
- Disable CPU rewrite mode.
- Disable voltage detection.
- Set the PHISRS bit in the CKRSCR register to 1 (no division).
- Set the WAITRS bit in the CKRSCR register to 0 (return from wait mode using the system base clock immediately before entering wait mode).
- Set the FMR27 bit to 0 (low-current-consumption read mode disabled).
- Set the WTFMSTP bit to 1 (flash memory stops in wait mode).
- Set the LPE bit in the VCA2 register to 1 (low-power-consumption wait mode enabled).

(4) Enable maskable interrupts and execute the WAIT instruction to enter wait mode.
(5) Return from wait mode using the time RJ2 interrupt (1 second period). Clocks set in (3) are selected for the CPU clock when returning from wait mode.
(6) Oscillate the XIN clock by a program.
(7) After waiting until XIN clock oscillation stabilizes, switch the system base clock from the low-speed on-chip oscillator to the XIN clock, and enter high-speed clock mode (no division).

Figure 5.1 shows an Operating Example in Wait Mode.

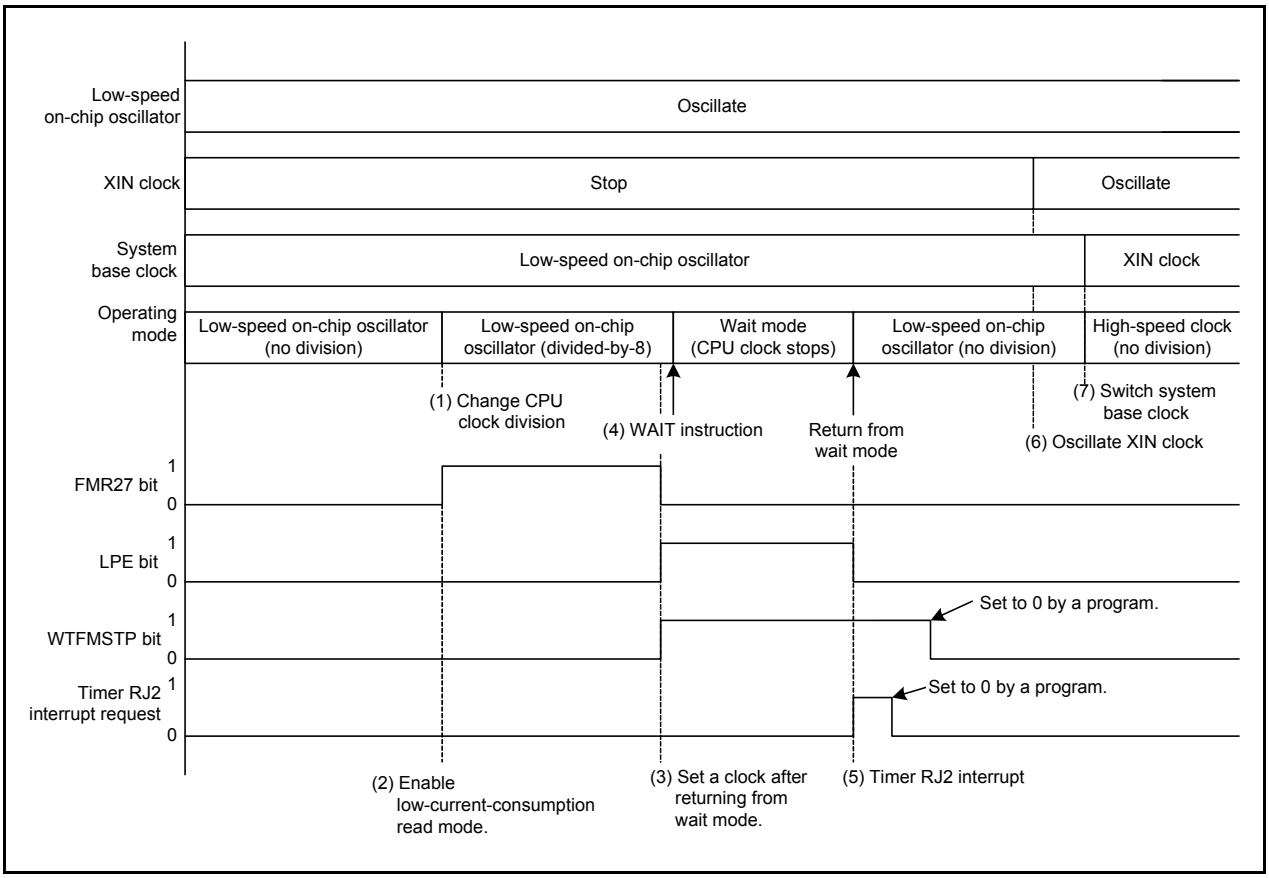


Figure 5.1 Operating Example in Wait Mode

5.2 Required Memory Size

Table 5.1 lists the Required Memory Size.

Table 5.1 Required Memory Size for Sample Program 2

Memory Used	Size	Remarks
ROM	311 bytes	In the r01an0370_src_sample2.c module
RAM	0 bytes	In the r01an0370_src_sample2.c module
Maximum user stack usage	10 bytes	
Maximum interrupt stack usage	18 bytes	

The required memory size varies depending on the C compiler version and compile options.

5.3 Functions

Table 5.2 lists the Functions.

Table 5.2 Functions

Function Name	Outline
mcu_init	System clock setting
timer_rj2_init	Initial setting of timer RJ2
power_control	Wait mode processing
_timer_rj	Timer RJ2 interrupt handling

5.4 Function Specifications

The following tables list the sample code function specifications.

mcu_init	
Outline	System clock setting
Header	None
Declaration	void mcu_init(void)
Description	Set the system clock.
Argument	None
Returned value	None
Remark	—

timer_rj2_init	
Outline	Initial setting of timer RJ2
Header	None
Declaration	void timer_rj2_init(void)
Description	Perform initial setting to use timer RJ2 in timer mode.
Argument	None
Returned value	None
Remark	—

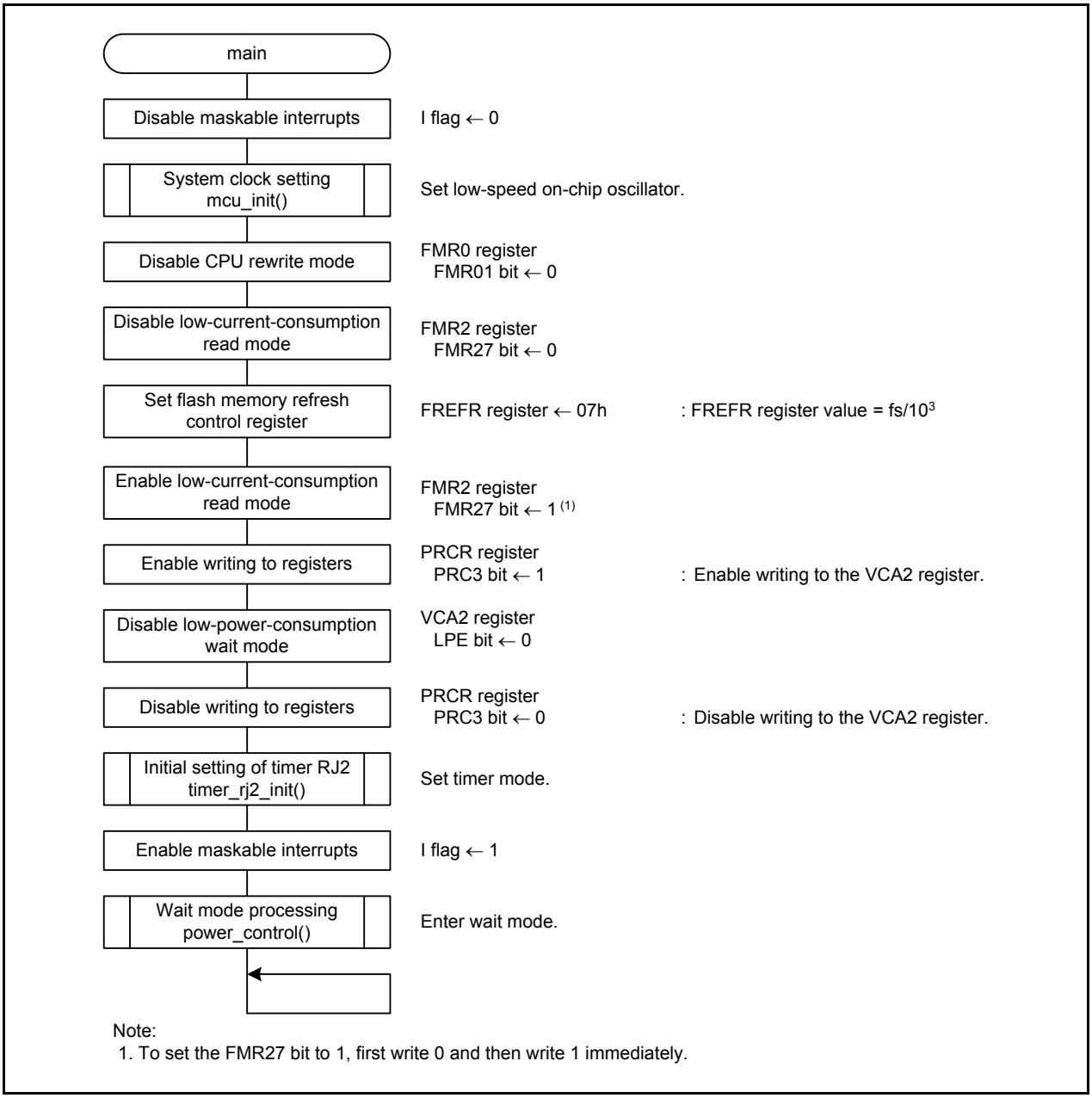
wait_control	
Outline	Wait mode processing
Header	None
Declaration	void power_control(void)
Description	Enter wait mode.
Argument	None
Returned value	None
Remark	—

_timer_rj2	
Outline	Timer RJ2 interrupt handling
Header	None
Declaration	void _timer_rj(void)
Description	Perform timer RJ2 interrupt handling.
Argument	None
Returned value	None
Remark	—

5.5 Flowcharts

5.5.1 Main Processing

Figure 5.2 shows the Main Processing.



Note:
1. To set the FMR27 bit to 1, first write 0 and then write 1 immediately.

Figure 5.2 Main Processing

5.5.2 System Clock Setting

Figure 5.3 shows the System Clock Setting.

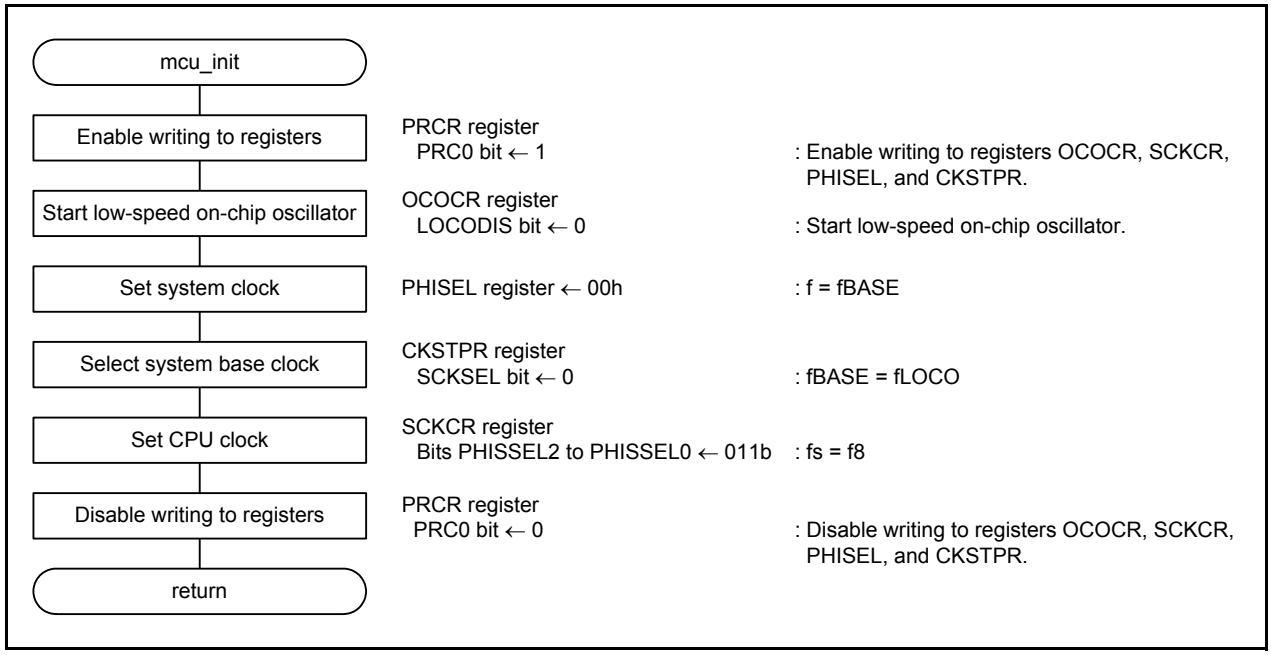


Figure 5.3 System Clock Setting

5.5.3 Initial Setting of Timer RJ2

Figure 5.4 shows the Initial Setting of Timer RJ2.

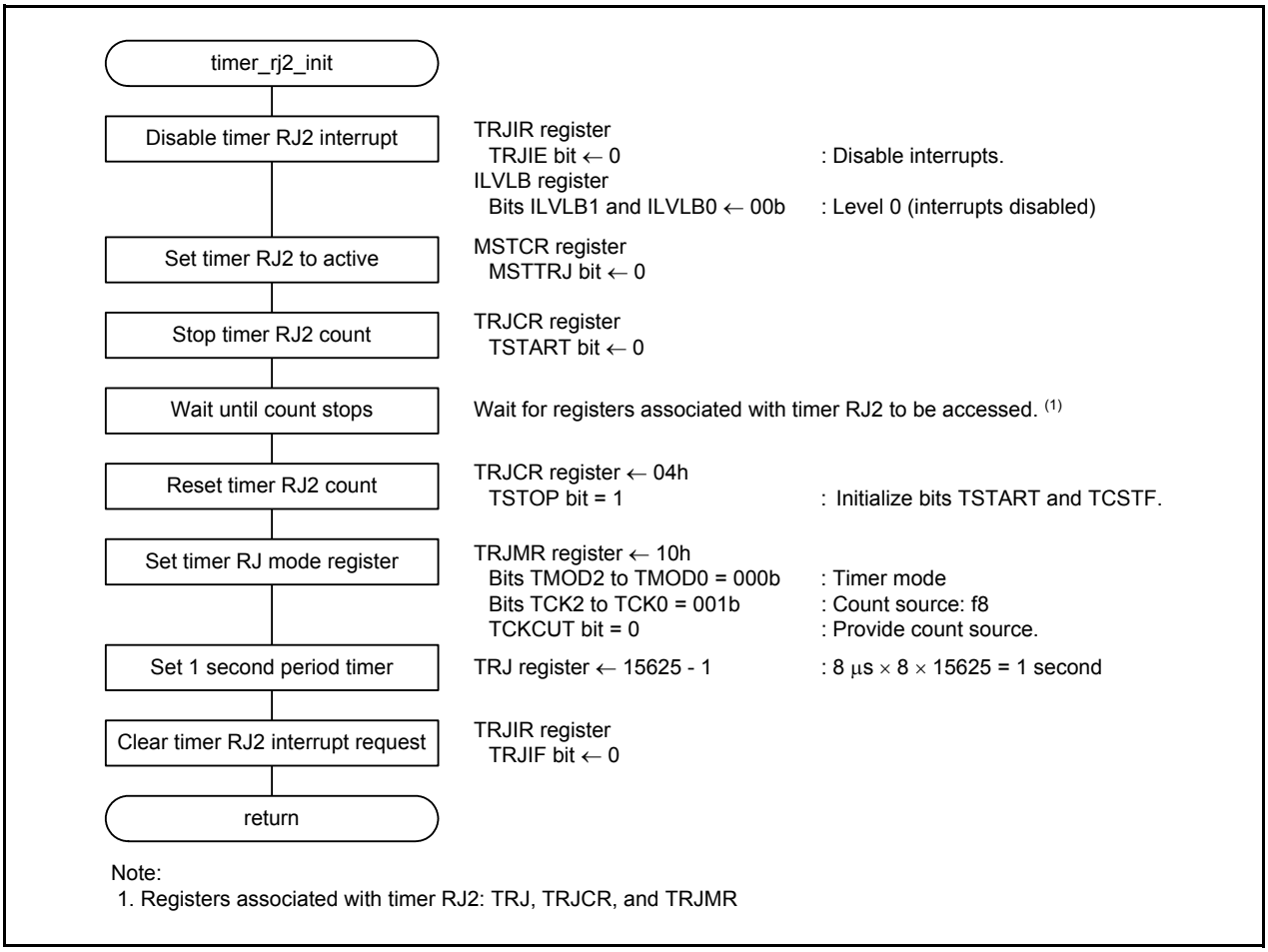


Figure 5.4 Initial Setting of Timer RJ2

5.5.4 Wait Mode Processing

Figure 5.5 and 5.6 show Wait Mode Processing.

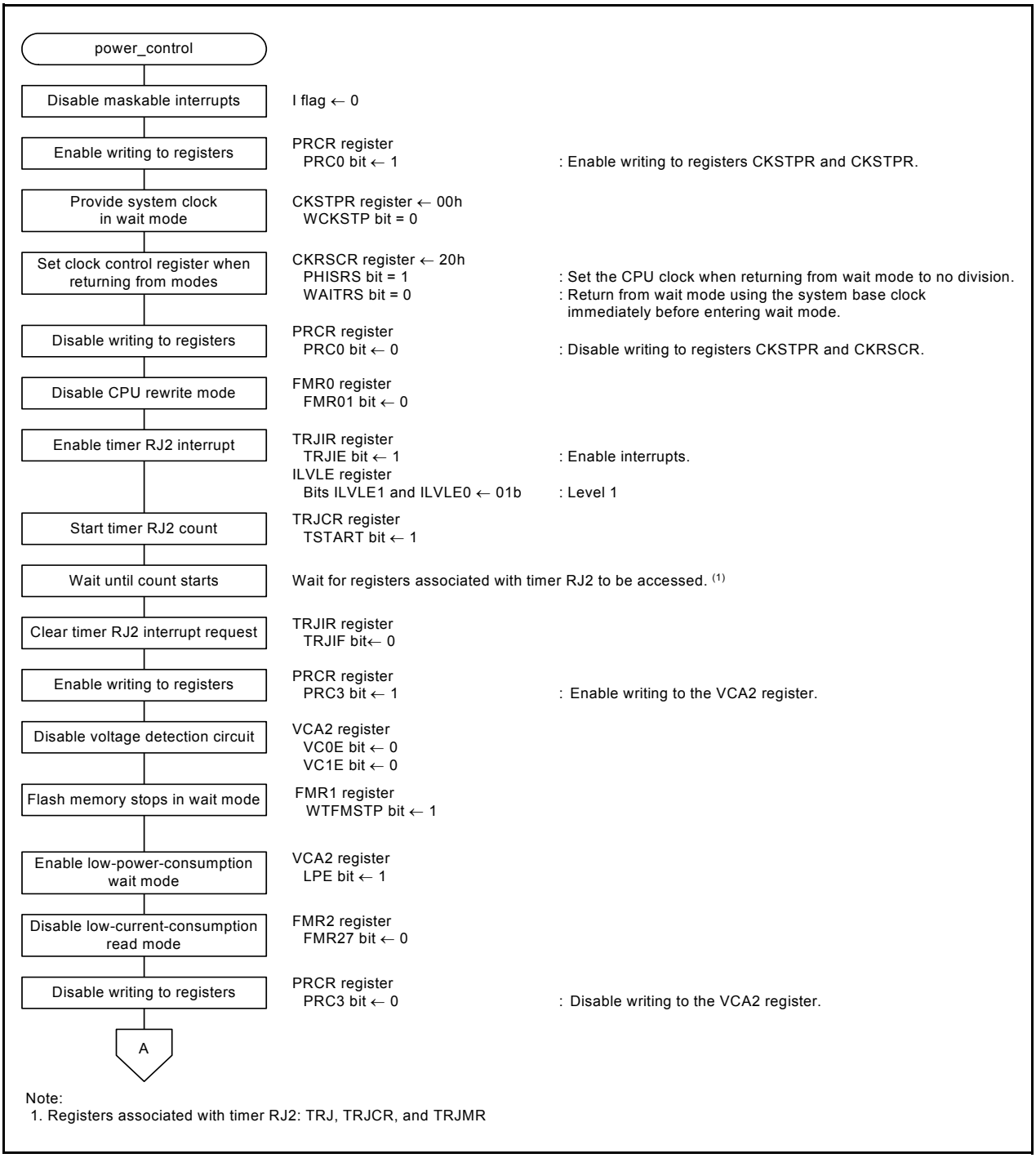


Figure 5.5 Wait Mode Processing (1/2)

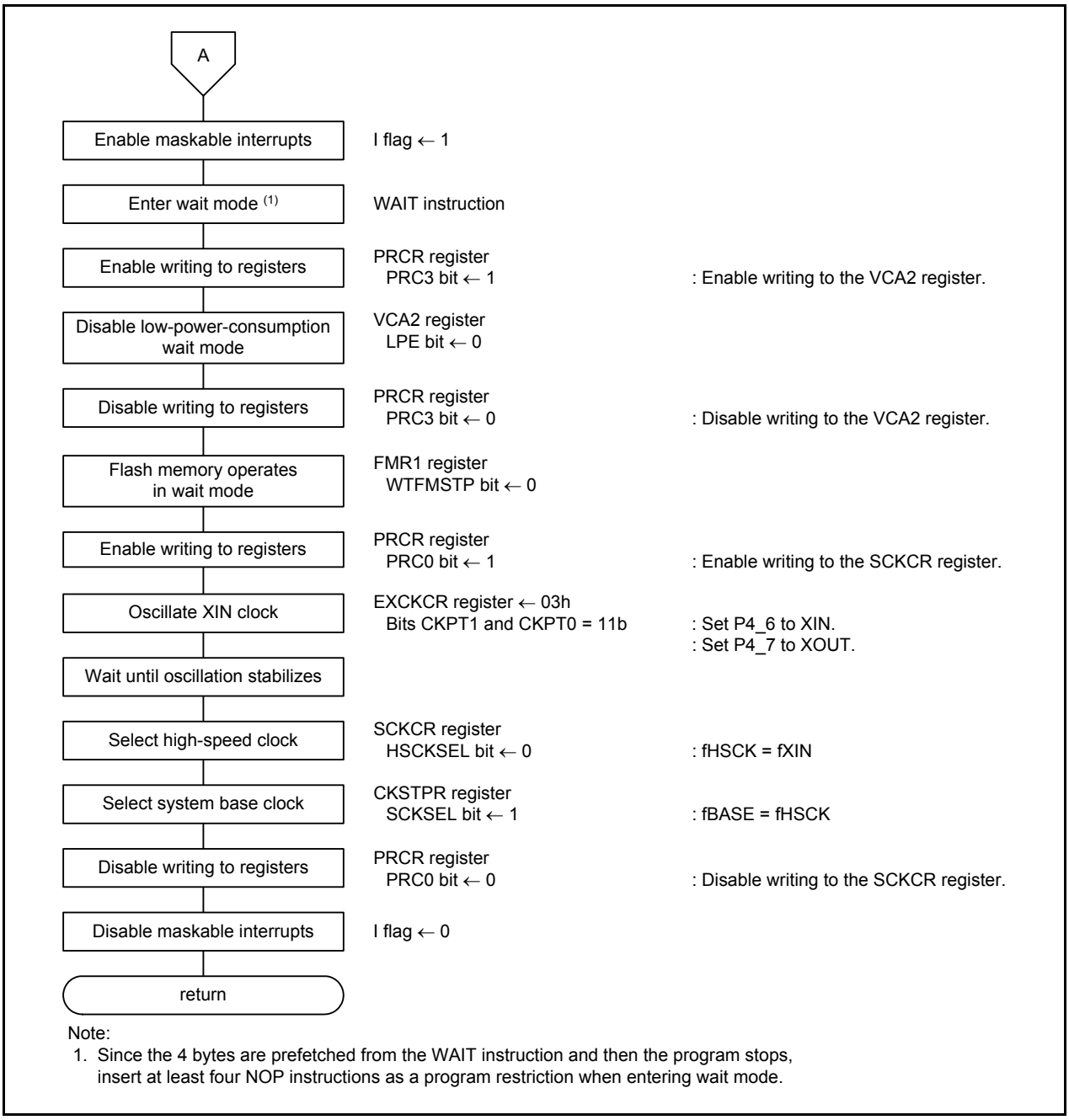


Figure 5.6 Wait Mode Processing (2/2)

5.5.5 Timer RJ2 Interrupt Handling

Figure 5.7 shows Timer RJ2 Interrupt Handling.

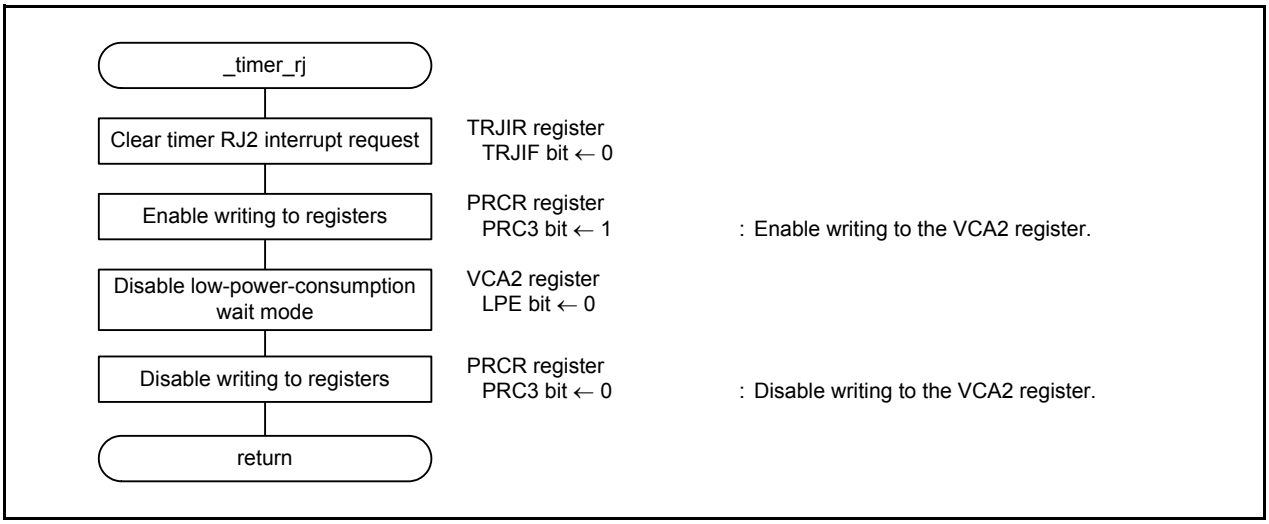


Figure 5.7 Timer RJ2 Interrupt Handling

6. Sample Code

Sample code can be downloaded from the Renesas Electronics website.

7. Reference Documents

R8C/M12A Group User's Manual: Hardware Rev.1.00
The latest version can be downloaded from the Renesas Electronics website.

Technical Update/Technical News
The latest information can be downloaded from the Renesas Electronics website.

C Compiler Manual
M16C Series, R8C Family C Compiler Package V.5.45
C Compiler User's Manual Rev.2.00
The latest version can be downloaded from the Renesas Electronics website.

Website and Support

Renesas Electronics website
http://www.renesas.com/

Inquiries
http://www.renesas.com/inquiry

Revision History	R8C/M12A Group Power Control in Wait Mode

Rev.	Date	Description	
		Page	Summary
1.00	Sep. 16, 2011	—	First edition issued

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General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.

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